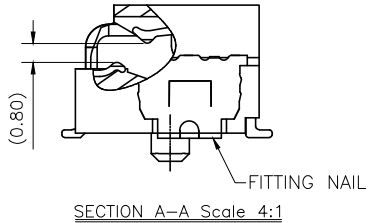
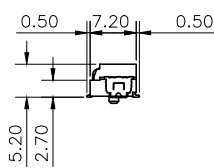
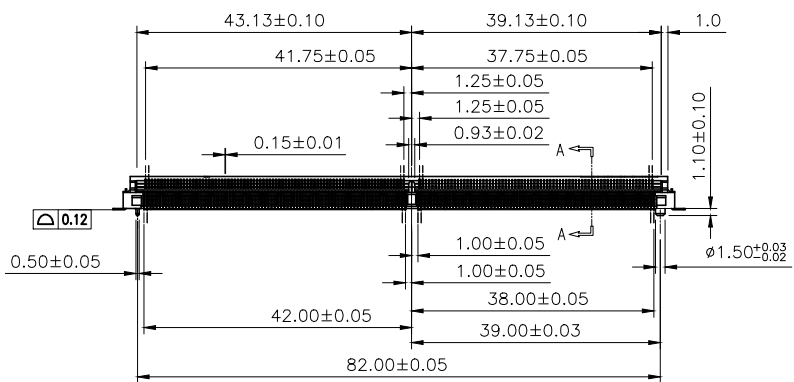
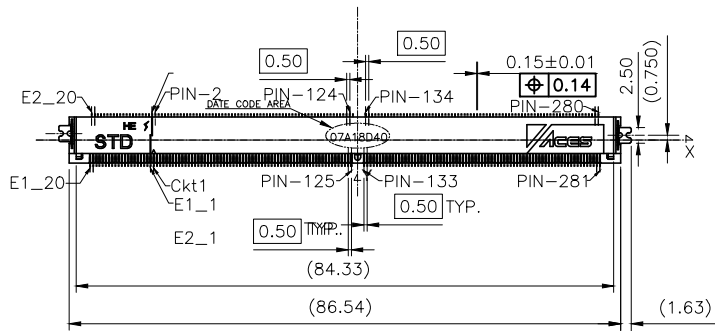




A B C D E F



- NOTES:
- MATERIAL:
 - HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR: BLACK.
 - CONTACT: COPPER ALLOY
 - FITTING NAIL: COPPER ALLOY
 - BOARD LOCK: COPPER ALLOY
 - FINISH:
 - CONTACT:
 - UNDERPLATING: 50u" MIN. NICKEL OVERALL.
 - 8: GOLD 3u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
 - M: GOLD 3u" ON CONTACT AREA AND SOLDER TAIL
 - T: GOLD 10u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
 - C: GOLD 15u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA
 - D: GOLD 30u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA
 - FITTING NAIL:
 - UNDERPLATING: 50u" MIN. NICKEL OVERALL.
 - FINISH: 100~200u" MATT TIN OVER ALL
 - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
 - ROHS COMPLIANT PRODUCT.
 - SPEC. PLS. REFER TO PS-91781-xxxx
 - PACKING SPEC. PLS. REFER TO 91781-314xx(TRAY)
 - PACKING SPEC. PLS. REFER TO 91781-314xx(REEL)
 - SUGGESTION: PLS PAY ATTN TO THE DEFORMATION DIRECTION OF PCB-SMT IN CONNECTOR LAYOUT AREA
 - THE PCB WARPAGE : 0.05MAX.
 - THE PCB Coplanarity : 0.08MAX.(ex.86.54mm&CONN.LAYOUT AREA).
 - PART NUMBER

91781-XXX X X-XXX

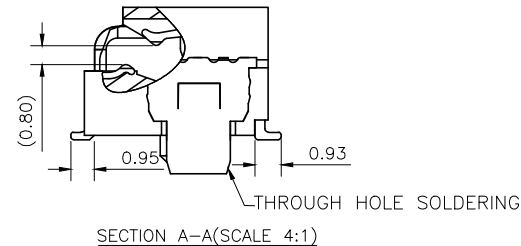
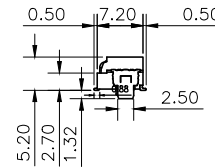
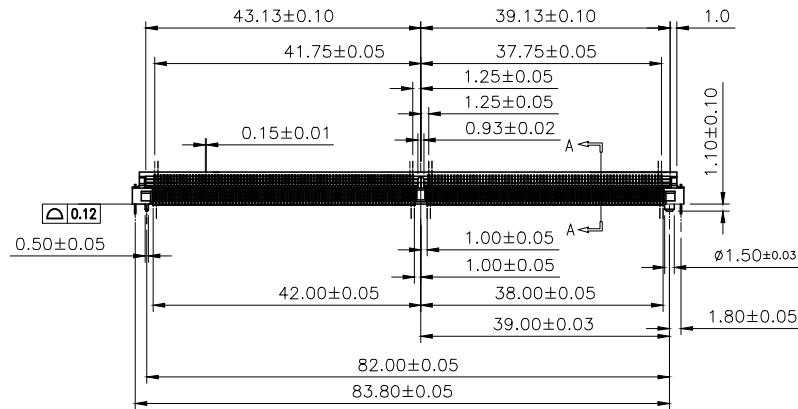
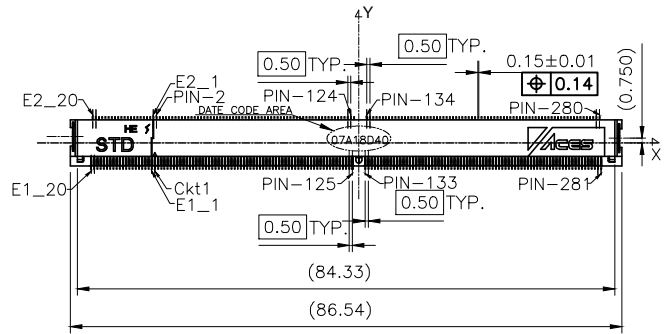
NO OF CKT	XXX	F/N POLARIZATION
314: 314 PIN	001	SMT (SEE SHEET-1)
PACKING	002	THROUGH HOLE(SEE SHEET-2)
0:REEL		
2:TRAY		
U:REEL(PLASTIC)		

- PLATING
- 8: GOLD 3u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
 - M: GOLD 3u" MIN ON CONTACT AREA AND SOLDER TAIL
 - T: GOLD 10u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
 - C: GOLD 15u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA
 - D: GOLD 30u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA

1
2
3
4
5

QUALITY SYMBOLS MAJOR Ⓜ CRITICAL Ⓢ GENERAL TOLERANCES (UNLESS SPECIFIED) X ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Zhang,hongjun DATE 19/01/23		TITLE MXM-3 314 PINS 0.5mm PITCH EDGE CARD CONN. SMT D/R R/A STD TYPE H=5.2mm (BTB H=2.7)
	CHECKED BY Lu, Jing Quan DATE 19/01/23		
	UNITS mm		SIZE A4
	SCALE 2 : 1	SHEET NO. 1 OF 5	DWG NO. 91781-314XX-XXX REV E PART NO. SEE NOTES

B C D E F



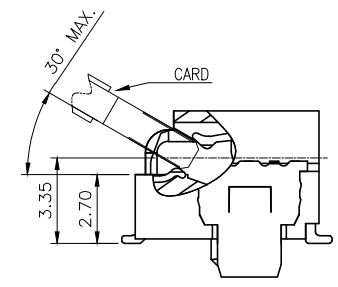
NOTES:

1. MATERIAL:
 - 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR: BLACK.
 - 1.2 CONTACT: COPPER ALLOY
 - 1.3 FITTING NAIL: COPPER ALLOY
 - 1.4 BOARD LOCK: COPPER ALLOY
2. FINISH:
 - 2.1 CONTACT:
 - UNDERPLATING: 50u" MIN. NICKEL OVERALL.
 - 8: GOLD 3u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
 - M: GOLD 3u" ON CONTACT AREA AND SOLDER TAIL
 - T: GOLD 10u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
 - C: GOLD 15u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA
 - D: GOLD 30u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA
 - 2.2 FITTING NAIL:
 - UNDERPLATING: 50u" MIN. NICKEL OVERALL.
 - FINISH: 100~200u" MATT TIN OVER ALL
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
4. ROHS COMPLIANT PRODUCT.
5. SPEC. PLS. REFER TO PS-91781-xxxx
6. PACKING. SPEC. PLS. REFER TO 91781-314xx(TRAY)
7. PACKING SPEC. PLS. REFER TO 91781-314xx(REEL)
8. SUGGESTION: PLS PAY ATTN TO THE DEFORMATION DIRECTION OF PCB-SMT IN CONNECTOR LAYOUT AREA
9. THE PCB WARPAGE : 0.05MAX.
10. THE PCB Coplanarity : 0.08MAX.(ex.86.54mm&CONN.LAYOUT AREA).
11. PART NUMBER

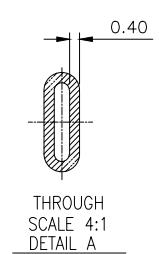
91781-XXX X X-XXX	
NO OF CKT	XXX F/N POLARIZATION
314: 314 PIN	001 SMT (SEE SHEET-1)
PACKING	002 THROUGH HOLE(SEE SHEET-2)
0: REEL	
2: TRAY	
U: REEL(PLASTIC)	

- PLATING
- 8: GOLD 3u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
 - M: GOLD 3u" MIN ON CONTACT AREA AND SOLDER TAIL
 - T: GOLD 10u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
 - C: GOLD 15u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA
 - D: GOLD 30u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA

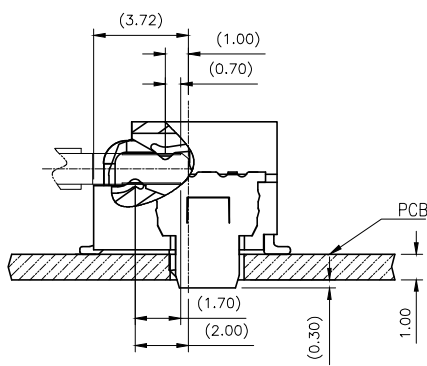
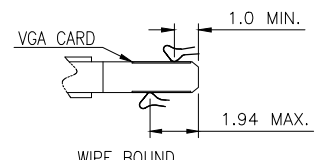
QUALITY SYMBOLS	DRAWN BY	DATE				
MAJOR	Zhang, hongjun	19/01/23				
CRITICAL	CHECKED BY	DATE	TITLE MXM-3 314 PINS 0.5mm PITCH EDGE CARD CONN. SMT D/R R/A STD TYPE H=5.2mm (BTB H=2.7)			
GENERAL TOLERANCES (UNLESS SPECIFIED)	Lu, Jing Quan	19/01/23				
X. ±0.5	APPROVED BY	DATE	UNITS	SIZE	DWG NO.	
.X ±0.25	hsieh, fu yu	19/01/23	mm		A4	91781-314XX-XXX
.XX ±0.15			SCALE	SHEET NO.	REV	PART NO.
.XXX ±0.1			2:1	2 OF 5	E	SEE NOTES
ANGLES ±2°						



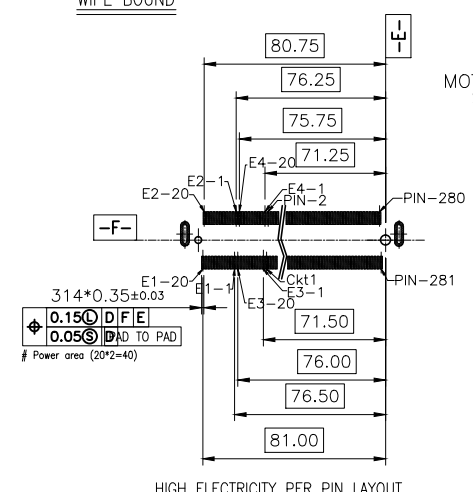
PCB 30° MAX In conn. Scale 4:1



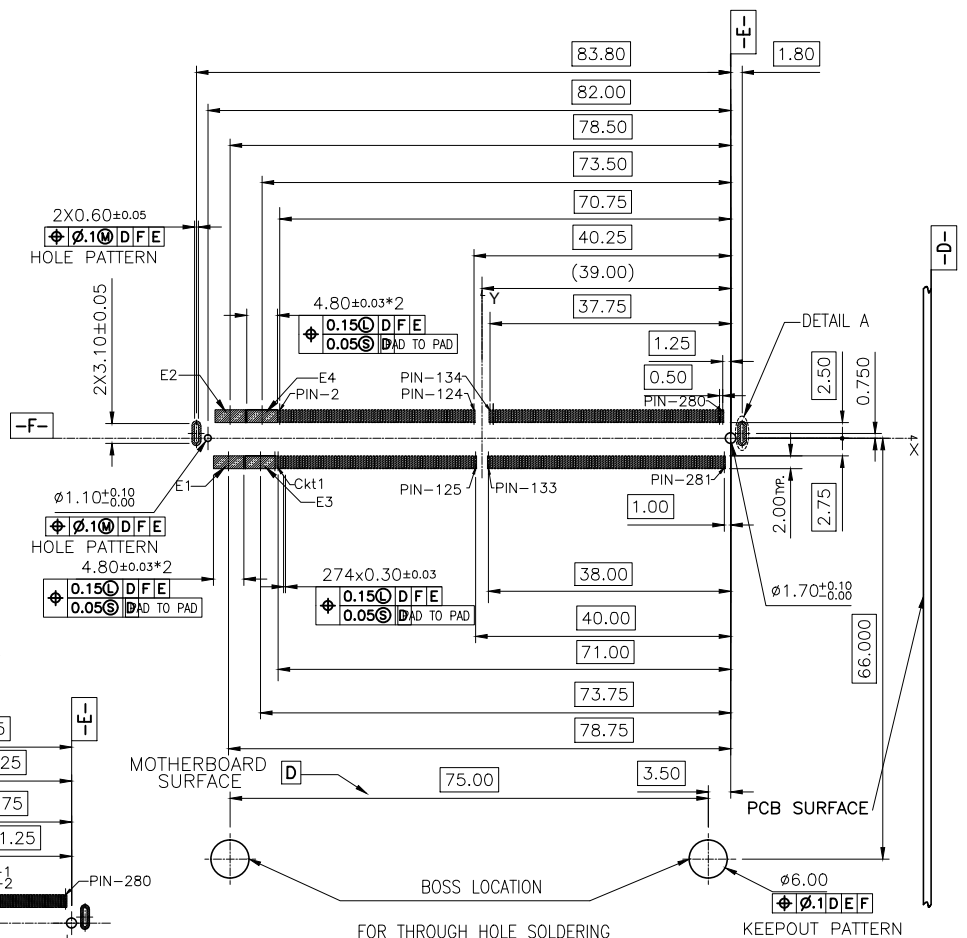
THROUGH HOLE SCALE 4:1 DETAIL A



PCB on 90° Scale 4:1



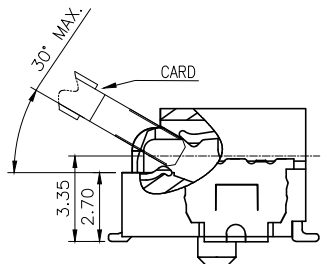
HIGH ELECTRICITY PER PIN LAYOUT



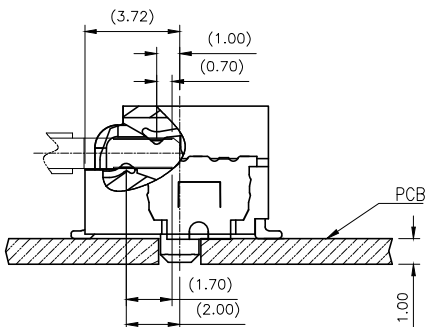
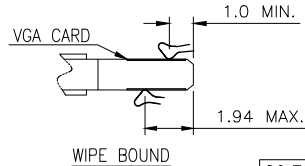
FOR THROUGH HOLE SOLDERING
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

KEEPOUT PATTERN

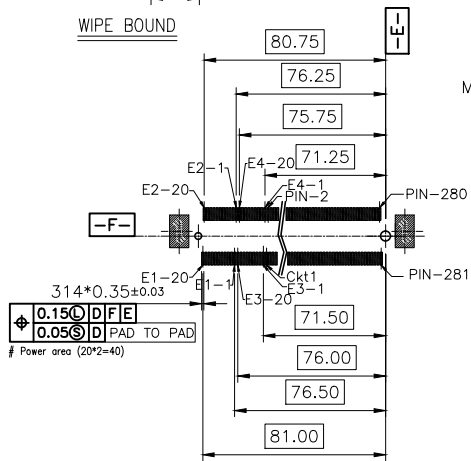
QUALITY SYMBOLS MAJOR CRITICAL GENERAL TOLERANCES (UNLESS SPECIFIED) X ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Zhang, hongjun	DATE 19/01/23	
	CHECKED BY Lu, Jing Quan	DATE 19/01/23	
	APPROVED BY hsieh, fu yu	DATE 19/01/23	SMT D/R R/A STD TYPE H=5.2mm (BTB H=2.7)
	UNITS mm		SIZE A4
	SCALE 2:1	SHEET NO. 3 OF 5	DWG NO. 91781-314XX-XXX
		REV E	PART NO. SEE NOTES



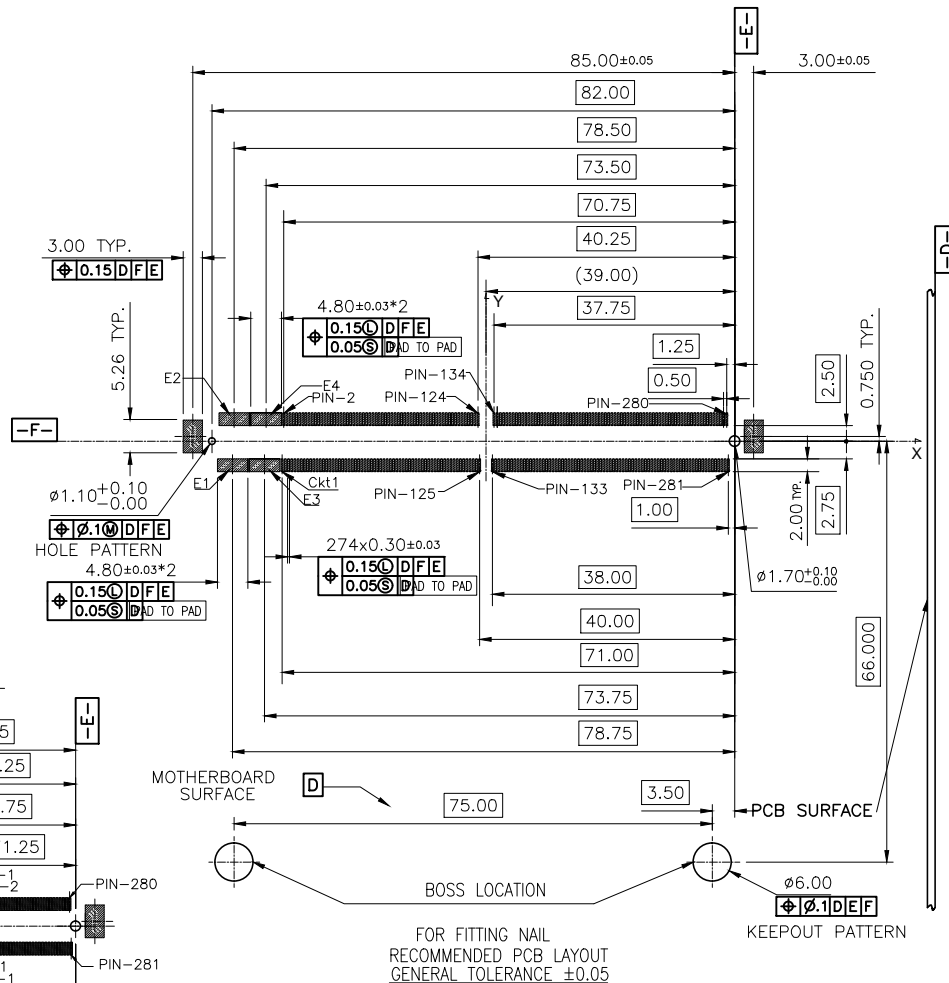
PCB 30° MAX In conn. Scale 4:1



PCB on 90° Scale 4:1

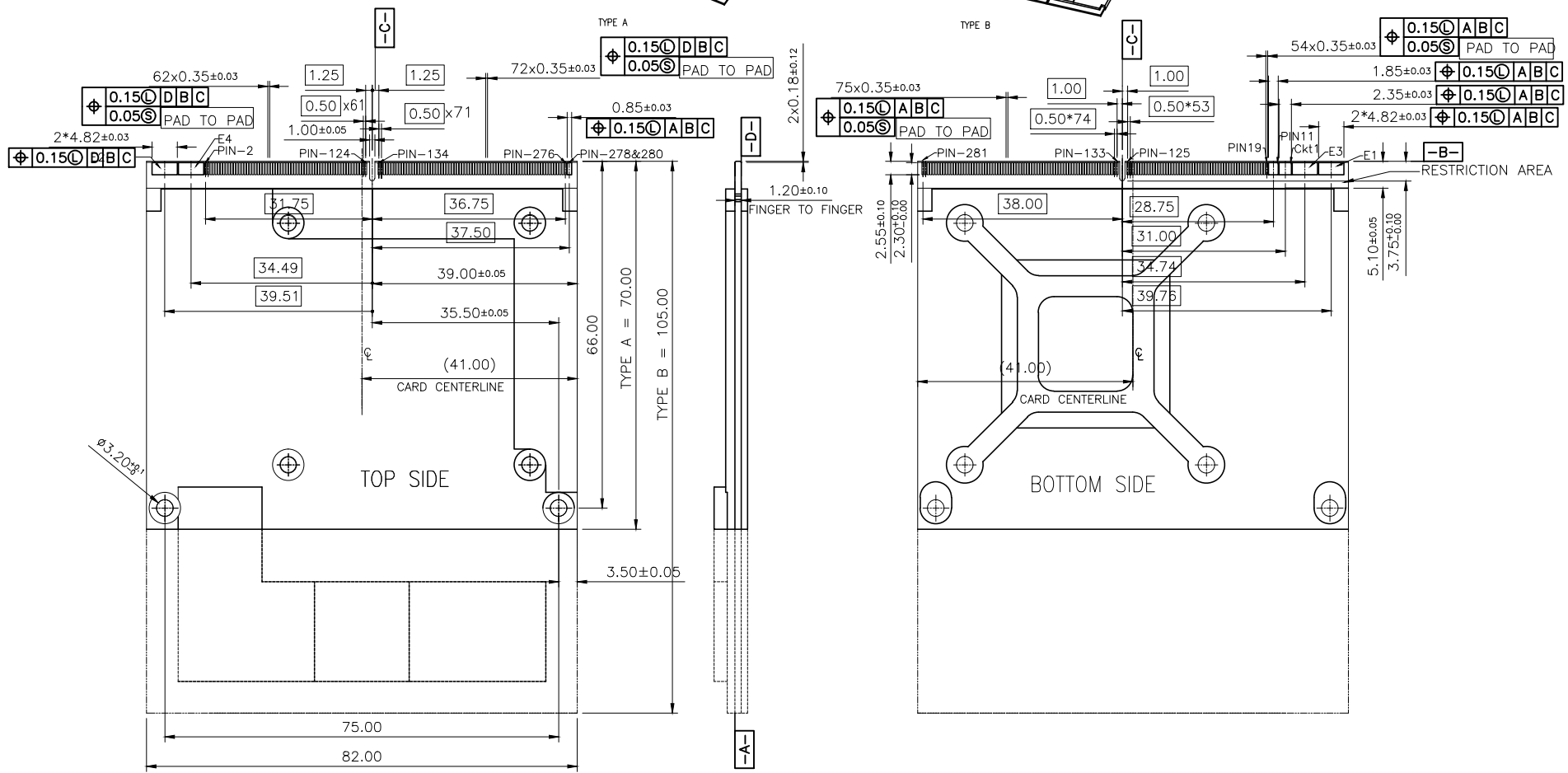
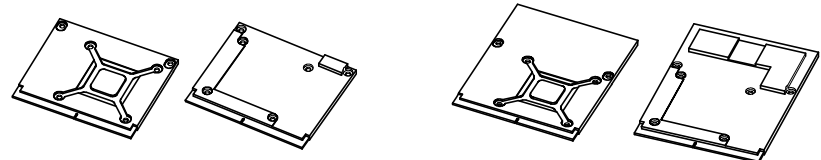


HIGH ELECTRICITY PER PIN LAYOUT



FOR FITTING NAIL
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

QUALITY SYMBOLS MAJOR Ⓜ CRITICAL Ⓢ GENERAL TOLERANCES (UNLESS SPECIFIED) X ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Zhang,hongjun	DATE 19/01/23	ACES ELECTRONICS TITLE MXM-3 314 PINS 0.5mm PITCH EDGE CARD CONN. SMT D/R R/A STD TYPE H=5.2mm (BTB H=2.7)
	CHECKED BY Lu, Jing Quan	DATE 19/01/23	
	APPROVED BY hsieh, fu yu	DATE 19/01/23	REV E
	UNITS mm		SCALE 2:1
	SHEET NO. 4 OF 5		PART NO. SEE NOTES



MXM-3 314PIN GOLD FINGER
 MXM-3 MAX 321 CONTACT LOCATION
 314 USEABLE (7 LOST TO KEY)

QUALITY SYMBOLS MAJOR CRITICAL	DRAWN BY	DATE	
	Zhang,hongjun	19/01/23	
GENERAL TOLERANCES (UNLESS SPECIFIED) X ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	CHECKED BY	DATE	TITLE MXM-3 314 PINS 0.5mm PITCH EDGE CARD CONN. SMT D/R R/A STD TYPE H=5.2mm (BTB H=2.7)
	Lu, Jing Quan	19/01/23	
	APPROVED BY	DATE	UNITS mm
	hsieh, fu yu	19/01/23	
	SCALE	SHEET NO.	SIZE A4
	2 : 1	5 OF 5	DWG NO. 91781-314XX-XXX
			REV E
			PART NO. SEE NOTES